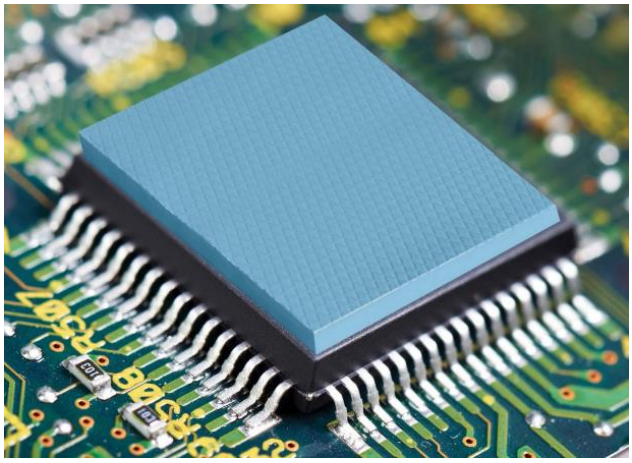
MATRIX

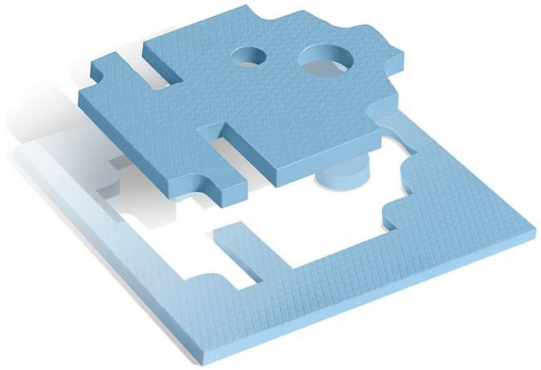
Thermally Conductive Low Compression Force Gap Filler Pad



Parker Chomerics THERM-A-GAP™ PAD 30 is a thermally conductive, electrically isolating gap filler pad with a thermal conductivity of 3.2 W/m-K. Designed to provide effective heat transfer between electronic devices, heat sinks, or other cooling features, THERM-A-GAP PAD 30 offers the ideal combination of heat transfer, low outgassing, and low compressing forces. With a Shore 00 hardness measurement of 30, it is designed to maintain conformability in gaps that contain uneven mating surfaces, air gaps, or where rough surface texture is a concern. THERM-A-GAP PAD 30 was developed to be a universal solution across applications and industries requiring a moderate level of thermal performance in electronic device designs. It is a cost-effective solution and optimized for flexibility of design with several material carrier options available and ease of customizati unique shapes and sizes.

PRODUCT FEATURES:

- 3.2 W/m-K thermal conductivity
- Very low compression force
- Very good thermal conductivity
- High tack surface reduces contact resistance
- “A” version offers high strength acrylic PSA for permanent attachment
- UL recognized V-0 flammability
- RoHS compliant
- Vibration dampening



IDEAL APPLICATIONS:

- Telecommunications equipment
- Consumer electronics
- Automotive electronics (ECUs)
- LEDs and lighting
- Power conversion
- Desktop computers, laptops, servers
- Handheld devices
- Memory modules

Authorized Canadian Partner

Parker | Chomerics

AVAILABLE SIZES:

- 0.020” to 0.200”
- Matrix can precision cut to custom part sizes

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www.matrixtechnology.ca

MATRIX

MATRIX PRECISION CONVERTING

Your Application. Our Expertise.

Matrix specializes in precision cutting and converting of engineered materials to meet the exact specifications required by manufacturers. Our state-of-the-art equipment and expertise ensure precise customization, providing manufacturers with streamlined solutions to enhance their product quality and performance.

THERM-A-GAP PAD 30			
	Typical Properties†	PAD 30	Test Method
Physical	Color	Blue	Visual
	Carrier Options: G = Woven glass - no pressure sensitive adhesive (PSA) A = Aluminum foil - with PSA PN = PEN film KT = Thermally enhanced polyimide No letter suffix = None (unsupported)	PAD30G PAD30A PAD30PN PAD30KT PAD30	--
	Standard Thicknesses*, in. (mm)	0.020 – 0.200 (0.51 – 5.08)	ASTM D374
	Specific Gravity	2.9	ASTM D792
	Hardness, Shore 00	30	ASTM D2240
	Percent Deflection @ Various Pressures** (0.120 in thick sample) @ 5 psi (34 kPa) @ 10 psi (69 kPa) @ 25 psi (172 kPa) @ 50 psi (345 kPa)	% Deflected 17% 26% 38% 49%	ASTM C165 MOD (0.120 in with no Carrier, 0.50 in dia. probe, 0.025 in/min rate)
Thermal	Operating Temperature Range, °F (°C)	-67 to 392 (-55 to 200)	Chomerics
	Thermal Conductivity, W/m-K	3.2	ASTM D5470
	Thermal Impedance, °C-in²/W (°C-cm²/W) @ 10 psi, @ 0.04 in. (1mm) thick, "G" version	0.4 (2.6)	ASTM D5470
	Heat Capacity, J/g-K	1	ASTM E1269
	Coefficient of Thermal Expansion, ppm/K	150	ASTM E831
Electrical	Dielectric Strength, V_{AC}/mil (kV_{AC}/mm)	150 (5.9)	ASTM D149
	Volume Resistivity, ohm-cm	10^{13}	ASTM D257
	Dielectric Constant @ 1,000 kHz and at 0.039 (1mm) thick	7.7	ASTM D150
	Dissipation Factor @ 1,000 kHz and at 0.039 (1mm) thick	0.001	CHO-TM-TP13
Regulatory	Flammability Rating (See UL File E140244 for Details)	V-0	UL 94
	RoHS Compliant	Yes	Chomerics Certification
	Outgassing, % TML (% CVCM)	0.13 (0.03)	ASTM E595
	Shelf Life, months from date of shipment (PAD 30A)	36 (18)	Chomerics
	Storage Conditions, °F (°C) @ 50% Relative Humidity	50 to 90 (10 to 32)	Chomerics

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